

EVG SMART VIEW

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BRIEF DESCRIPTION

The SmartView NT automated bond alignment system for universal alignment offers a proprietary method for micron-level face-to-face wafer-level alignment.

RESEARCH SERVICES

- Wafer stacking for 3D interconnect, wafer-level packaging and high-volume MEMS devices.
- Bond pairs are aligned and clamped prior to loading into the bond chamber (for anodic, adhesive and glass frit bonding).
- Manual or fully automated configurations.
- Suitable for automated process line in 200 mm and 300 mm configurations.

METHODS & EXPERTISE ON THE RESEARCH INFRASTRUCTURE

Wafer stacking for 3D interconnect, wafer-level packaging and high-volume MEMS devices.

CONTACT

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